

International Application No.: PCT/JP2005/019286
U.S. Patent Application No.: Unknown
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IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following new Abstract of the Disclosure:

ABSTRACT OF THE DISCLOSURE

A multilayer substrate having a built-in chip-type electronic component includes a ceramic laminate having a plurality of ceramic layers, a chip-type electronic component disposed in the ceramic laminate and having an external terminal electrode, and a via conductor disposed in the ceramic layers in the lamination direction. The external terminal electrode of the chip-type electronic component is connected to the via conductor, and a connection step is provided in at least one of the upper and lower end surfaces of the via conductor.